

Spirflux 330® is a water based, organic nature, soft soldering flux

fitting into the German DIN Norm 8511 F-SW 23-25. Spirflux330® is used on metals which will not properly solder with conventional, even highly activated rosin based fluxes. Spirflux®330 avoids the need to use aggressive acid based fluxes of DIN group F-SW 11 and 12. Spirflux®330 is meant for use on light metal alloys, like Al, Mg, ..

Spirflux 330®

is a fully and easilay water soluble and highly solder- and base material- wetting formulation whose residues are easily dissolved in ordinary tap or DI (distille) or DM (demineralized, de-ionized) water. A water cleaning process is usually usually the least costly method as it avoids costly solvent or other VOC vapour creating cleaning fluids or formulations.

In the ideal case the residues of the Spirflux330 application are almost chemically neutral and, depending on the application might be left on the soldered joints.

Cleaning is however mandatory on any electric or electronic circuits on which minor conductivities created by traces of the resiudes might cause a problem.

Spirflux 330®

is a concentrated solution which can be diluted, depending on base material, up to three times with DI water.



Application Tips for Soldering:

Spirflux 330® is a complex, organic, water based flux related to DIN Norm 8511 groups F-SW 23-25.

Spirflux 330® in its raw form as delivered reacts slightly sour and should be stored only in plastic containers.

Spirflux 330® wetted parts should not be stored before the soldering process. A drying process delaying soldering up to 30 minutes could be tolerated. The wet composition reacts slightly sour and already at room temperature does develop a chemical "etching / cleaning" activity reducing oxide layers on exposed surfaces.

Spirflux 330® residues are very easily dilluted and removed by a simple water wash / rinse of the soldered part or the area. Residues will only dissolve in water. A water wash must be done **prior** any other cleaning process.

Printed circuit boards / assemblies (PCB / PCA) should never be stored without a prior water rinse / cleaning and eventual neutralizing process. Always perform a water cleaning process.

Spirflux330® can be diluted with distilled water. The maximum possible dilution grade must be determined by a sequence of solder experiments in which the same materials are soldered with various Spirflux330® concentrations. As a guideline, the Spirflux330® can be diluted with an equal or double amount of DI water provided the solder area surface owns a reasonable level of solderability. Dillution also reduces the amount of left over residues.

Insulated cords or cables should not be soldered by dipping the wire end into the liquid flux. The Wicking of the strands will draw the flux into the stranded structure where it will not be anymore heated properly by the soldering heat applied and therefore might or will stay in its original slightly acid form.

On request, we can send you a sample for your testings.



Storage: Should be done in a cool (room temperature) and dark location. Do not allow Spirflux 330® to be frozen. This would deteriorate its function. Flaky floating parts in the flux indicate an exposure to a too low storage or transit temperature. The original reddish flux fluid color can fade over time but will not influence quality.

Shelf life: Virtually indefinite provided Spirflux330® is properly stored and container is kept closed. Never return or add a used volume of flux to fresh flux.

Spirflux 330® is available in standard 1 liter plastic bottles or on request also in larger containers.

Prices: on request

Warranties: The User will have to test that the **Spirflux 330®** is fit for his application. Spirig can not take any responsibility that **Spirflux 330®** yields the requested solder results. User will have to verify this by his own tests. Samples might have to be tested and aged in a climatic chamber.

Spirflux® is a registered trademark of Spirig Switzerland.